WLCSP8 1.57x1.57x0.582
CASE 567PZ
ISSUE O

DATE 31 OCT 2016

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

RECOMMENDED LAND PATTERN (NSMD)

NOTES:
A. NO JEDEC REGISTRATION APPLIES.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
D. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
E. PACKAGE TYPICAL HEIGHT IS 582 MICRONS ± 43 MICRONS (539-625 MICRONS).
F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
G. BALL COMPOSITION: Sn95.5-Ag3.9-Cu0.6

DOCUMENT NUMBER: 98AON13313G
STATUS: ON SEMICONDUCTOR STANDARD
NEW STANDARD: WLCSP8 1.57x1.57x0.582

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